L Number	Hits	Search Text	DB	Time stamp
2	0	1t1.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:26
4	0	iti.as. and dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:27
5	0	iti.as. and ganged	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:27
3	155	iti.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:30
6	0	"Industrial Tools Incorporated".as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:31
7	116	ppss	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:31
8	0	ppss and dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:31
9	0	ppss and arbor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:31
10	0	ppss and gang	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:31
11	18307	dicing or dicer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:32
12	20341	gang or ganged	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:32
13	24675	arbor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:32
14	0	(dicing or dicer) with (gang or ganged) with arbor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:32
15	1	(dicing or dicer) same (gang or ganged) same arbor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:32

16	129	(gang or ganged) with arbor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:34
17	2421104	wafer semiconductor substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:33
18	22	((gang or ganged) with arbor) and (wafer semiconductor substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:33
19	146	(gang or ganged) same arbor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:34
20	26	((gang or ganged) same arbor) and (wafer semiconductor substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:34
21	4	(((gang or ganged) same arbor) and (wafer semiconductor substrate)) not (((gang or ganged) with arbor) and (wafer semiconductor substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 09:34